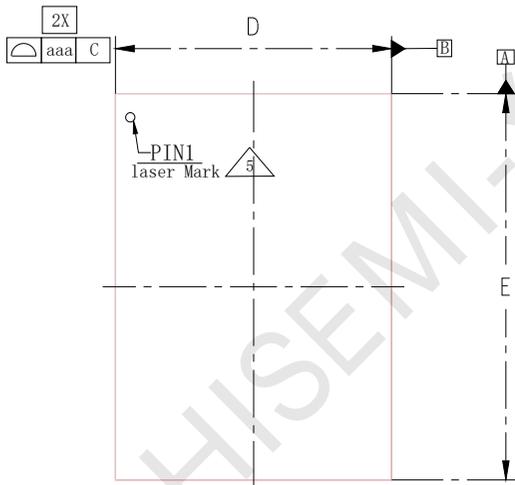
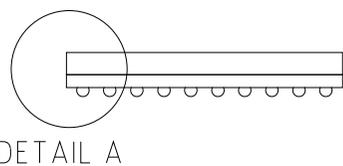


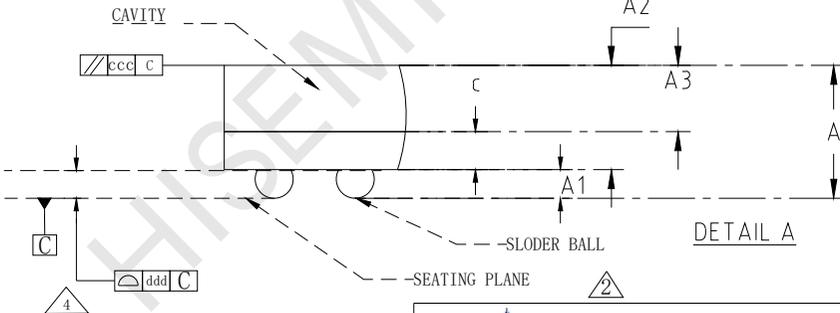
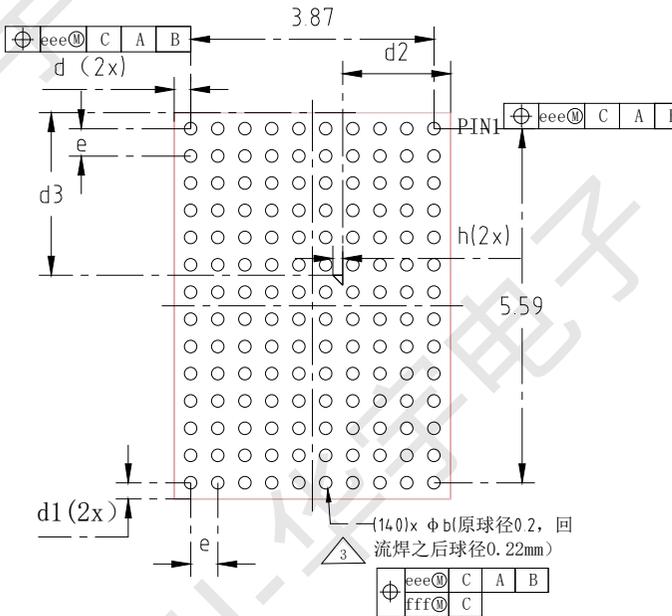
TOP VIEW  
正视图



SIDE VIEW  
侧视图



BOTTOM VIEW  
背视图



机械尺寸/mm

字符 SYMBOL	Dimension in mm			Dimension inch		
	最小值 MIN	典型值 NOMINAL	最大值 MAX	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	0.60	0.70	0.80	0.024	0.028	0.032
A1	0.10	0.15	0.20	0.004	0.006	0.008
A2	0.50	0.55	0.60	0.020	0.022	0.024
A3	0.300	0.350	0.400	0.012	0.014	0.016
c	0.170	0.200	0.230	0.007	0.008	0.009
D	4.3	4.4	4.5	0.169	0.173	0.177
E	6.0	6.1	6.2	0.236	0.240	0.244
b	0.15	0.20	0.25	0.006	0.008	0.009
e	0.430 BSC			0.0169 BSC		
d	0.215	0.265	0.315	0.0085	0.0104	0.0124
d1	0.205	0.255	0.305	0.0081	0.0100	0.0120
d2	1.670	1.720	1.770	0.065	0.067	0.069
d3	2.520	2.570	2.620	0.099	0.101	0.103
h	0.108	0.158	0.208	0.004	0.006	0.008
aaa	0.100			0.004		
ccc	0.100			0.004		
ddd	0.100			0.004		
eee	0.100			0.004		
fff	0.100			0.004		

TECHNOLOGY SPECIFICATION [技术要求]

1. BALL PAD OPENING: 0.180mm; [球形防焊开口: 0.180mm;]

④ PRIMARY DATUM C AND SEATING PLANE ARE THE SOLDER BALLS;

[主要基准C和底面是锡球;]

③ SDIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER,

PARALLEL TO PRIMARY DATUM C; [尺寸b是测量最大锡球直径, 平行于主要基准C;]

④ SPECIAL CHARACTERISTICS C CLASS: bbb, ddd; [特殊特性C类: ccc, ddd;]

⑤ THE PATTERN OF PIN 1 FIDUCIAL IS FOR REFERENCE ONLY;

[PIN 1标识仅供参考;]

6. BAN TO USE THE LEVEL 1 ENVIRONMENT-RELATED SUBSTANCES:

[禁止使用一级环境管理物质;]

**池州华宇电子科技股份有限公司**  
HiSEMI CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

HY-POD-BGA0162

PACKAGE OUTLINE DIMENSIONS  
FCBGA140B (4.4X6.1X0.7-0.43)

页数 page	单位 unit	比例 scale	视图 view
1	mm	1:1	☉ □

履历		
序号	内容	日期
1	新发行	2026.3.10

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制图核查: Drawing review	
审核: Checker	
核准: Approved	